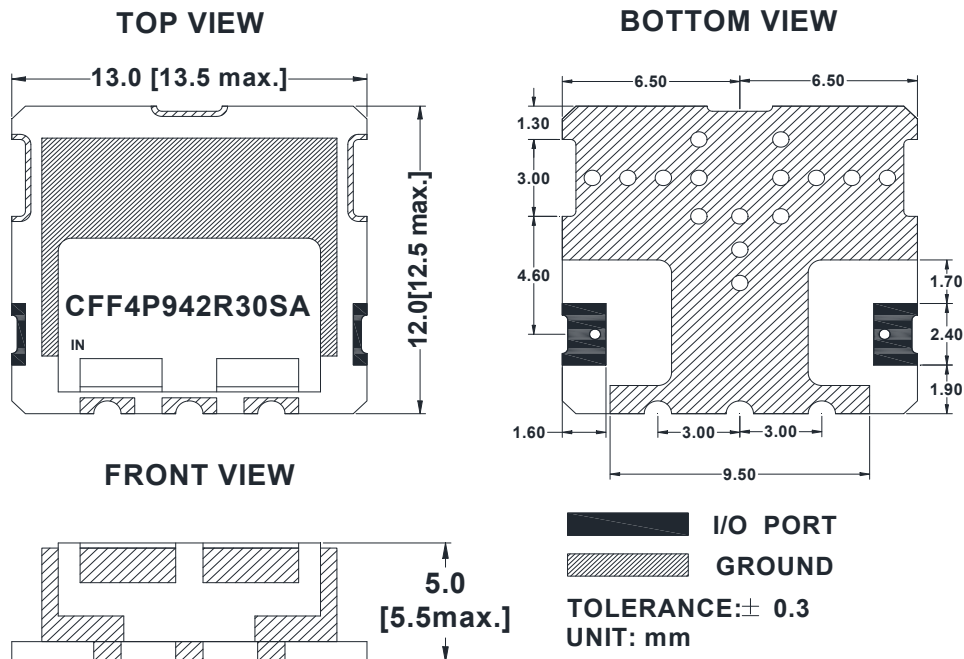


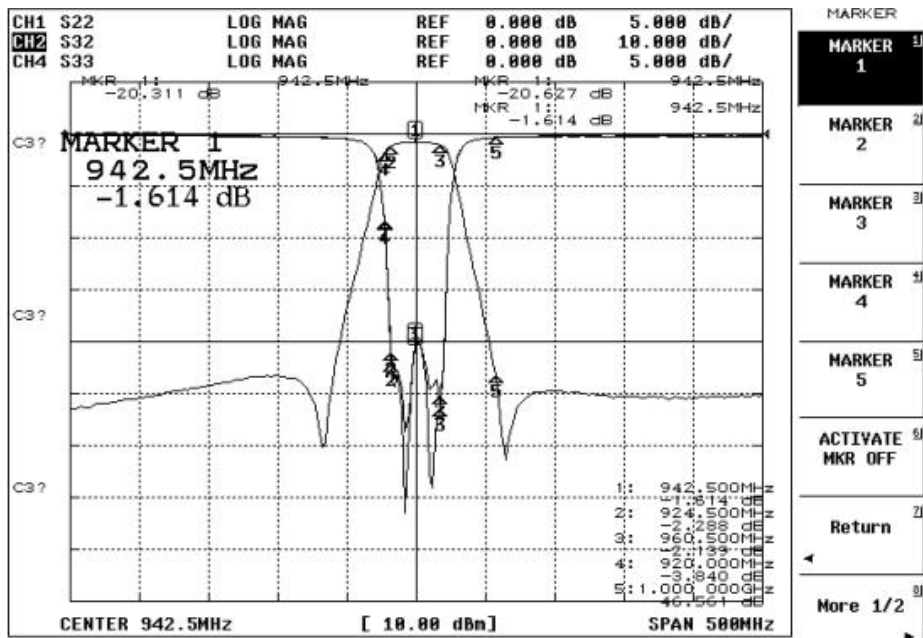
**Electrical Specification**

ITEMS	SPEC	UNIT
Center Frequency [fo]	942.5	MHz
Bandwidth [BW]	$f_{o\pm 18}$ [ 924.5 ~960.5 ]	MHz
Insertion Loss in BW	2.7	dB max
Ripple in BW	1.0	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	3.0 dB min. @ $f_{o\pm}$ [ 920.0 & ]	MHz
	45.0 dB min. @ $f_{o\pm}$ [ 1000.0 & ]	MHz
	dB min @ $f_{o\pm}$ [ & ]	MHz
	dB min @ $f_{o\pm}$ [ ~ ]	MHz
Group Delay Variation		ns max
Input Power	2.0	W max.
In/Out Impedance	50 $\Omega$	
Operation Temperature Range	-40°C to +85°C	

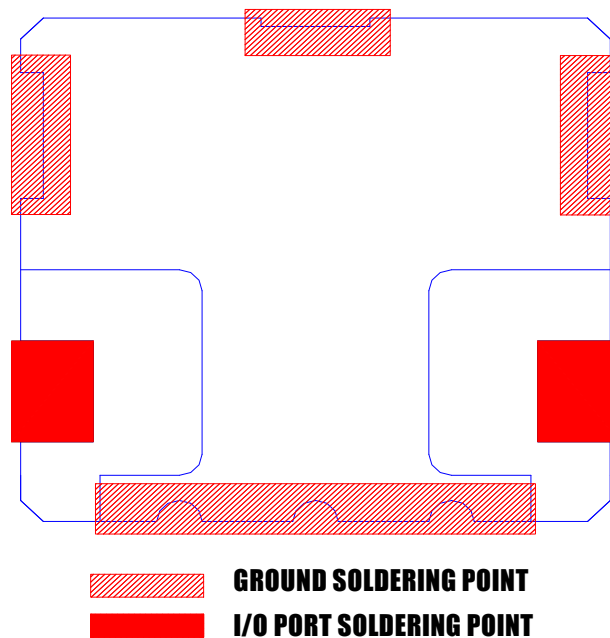
**Mechanical Specification**



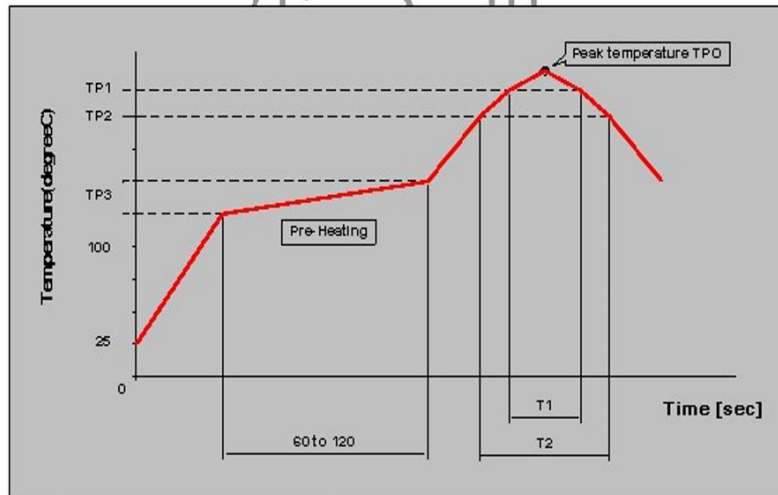
Plot Data



Recommended PC Board Pattern



 Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/-0	240	20	220	70	150 to 180